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## **FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #17007**

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**Issue Date:** 01-Mar-2013

**TITLE:** Final PCN for changing wire from gold to copper.

**PROPOSED FIRST SHIP DATE:** 1-Jun-2013

**AFFECTED CHANGE CATEGORY(S):** Wire Bonding and Mold resin

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or < [Satoshi.Yokoo@onsemi.com](mailto:Satoshi.Yokoo@onsemi.com) >

**SAMPLES:** Contact your local ON Semiconductor Sales Office or < [Akio.Nagahama@onsemi.com](mailto:Akio.Nagahama@onsemi.com) >

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or < [Satoru.Fujinuma@onsemi.com](mailto:Satoru.Fujinuma@onsemi.com) >

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

This is a Final Process Change Notification to announce for below contents.

- 1) Changing wire from gold to copper.
- 2) Changing Mold resin from Halogen to Halogen free.

The product design and electrical specifications will remain identical.

Reliability Qualification and full electrical characterization over temperature has been completed on the designated package qualification vehicles.


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**RELIABILITY DATA SUMMARY:**

Test Items	Test Condition	Test Time	Failure
Steady State Operating Life	Tj=Tjmax,Vcc=Operating max	1000h	0
Temperature Humidity Bias ※	Ta=85 degC,RH=85%,Vcc=Recommended	1000h	0
Temperature Cycle ※	Ta=-55 degC 30min. ⇔ Ta=150 degC 30min.	100Cycles	0
Pressure Cooker ※	Ta=121 degC,RH=100% 2.03x10 <sup>5</sup> Pa	50h	0
High Temperature Storage	Ta=150 degC	1000h	0
Resistance to Soldering heat (Reflow Soldering)	255 degC,10s(Peak 260 degC)	2times	0

Notice)

The test items with ※ mark are put into operation after the reflow soldering (at 255°C for 10seconds).

Judgment Criteria : Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

**ELECTRICAL CHARACTERISTIC SUMMARY:**

There is no change in the electrical performance. Datasheet specifications remain unchanged.

**List of affected General Parts:**

PART
LV8400V-TLM-E
LV8401V-TLM-E
LV8402V-TLM-E
LV8405V-TLM-E